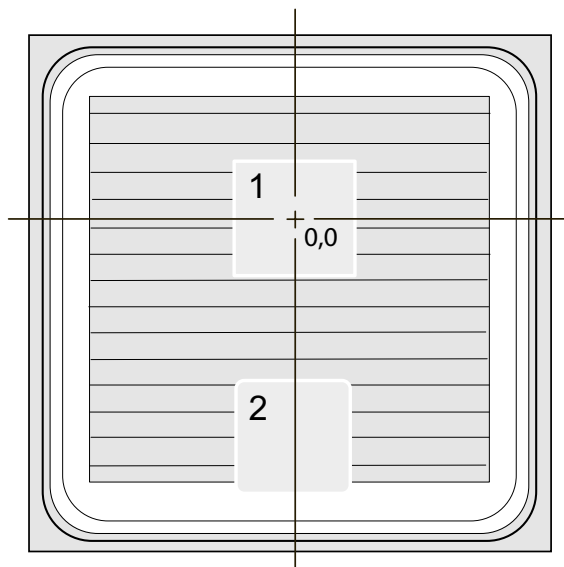


Pad Layout



Backside: Drain

Die Specifications

Device	Die Dimensions			Back Side Metal	Back Side	Bonding Pad Material
	Length ¹ (mils)	Width ¹ (mils)	Thickness (mils)			
2N6660	30	30	8.0 ± 1.0	Au	Drain	Al/Cu/Si

Bonding Pad Description

Pad #	Function	x Position ² (mils)	y Position ² (mils)	x Size (mils)	y Size (mils)
1	Source	0	0	5.5	6.0
2	Gate	0	-8.5	4.4	4.3

Notes:

1. Maximum values.
2. Position referenced to center of pad.

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